

Title (en)  
TWO-STEP MOLDING FOR A LEAD FRAME

Title (de)  
ZWEISTUFIGES FORMEN FÜR EINEN LEITERRAHMEN

Title (fr)  
MOULAGE EN DEUX ÉTAPES POUR UNE GRILLE DE CONNEXION

Publication  
**EP 3687758 B1 20230712 (EN)**

Application  
**EP 18815443 A 20181116**

Priority  
US 2018061597 W 20181116

Abstract (en)  
[origin: WO2020101706A1] Examples for a two-step insert molding process to encapsulate a pre- molded lead frame (104, 304, 504, 704) are described herein. In some examples, a first circuit component (106, 306, 506) and a first portion of a trace array (110, 310, 510) of the pre-molded lead frame for an integrated circuit (1C) assembly are encapsulated by a first insert molding component (112, 312, 512a, 512b, 712). The trace array connects the first circuit component to a second circuit component (108, 308, 508) of the pre-molded lead frame. A second portion of the trace array is encapsulated by a second insert molding component (114, 314, 514, 714).

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